

1N4448/1N4148/1N914B

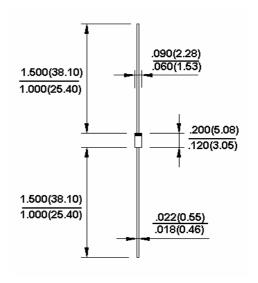
500 mW Hermetically Sealed Glas Fast Switching Diodes



DO-35

Features

- → Fast switching device (T_{RR}<4.0nS)
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- ♦ DO-35 package (JEDEC)
- Through-hole device type mounting
- ♦ Hermetically sealed glass
- Compression bonded construction
- All external surface are corrosion resistant and leads are readily solderable
- ♦ RoHS compliant
- ♦ Solder hot dip Tin(Sn) lead finish
- ♦ Cathode indicated by polarity band



Dimensions in inches and(millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Maximum Ratings

Type Number	Symbol	Value	Units
Power Dissipation	Pd	500	mW
Working Inverse Voltage	Wıv	75	V
Non-repetitive Peak Forward Current	lғм	450	mA
Average Rectified Current	lo	150	mA
Peak Forward Surge Current	I _{FSURGE}	2	Α
Operating Junction Temperature	T _J	175	°C
Storage Temperature Range	T _{STG}	-65 to + 200	°C

Electrical Characteristics

Type Number	Symbol	Min	Max	Units
Breakdown Voltage IR=100uA IR=5uA	B _V	100 75		V
Forward Voltage 1N4448, 1N914B IF=5.0mA 1N4148 IF= 10mA 1N4448, 1N914B IF =100m	VF	0.62	0.72 1.0 1.0	V
Reverse Leakage Current VR=20V VR=75V	lr		25 5	nA uA
Junction Capacitance VR=0, f=1.0MHz	Cj	_	4.0	pF
Reverse Recovery Time (Note 1)	trr	_	4.0	nS

Notes: 1. Reverse Recovery Test Conditions: I_F=10mA, VR=6V, R_L=100 Ω, I_{RR}=1mA



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RATINGS AND CHARACTERISTIC CURVES (1N4448/1N4148/1N914B)

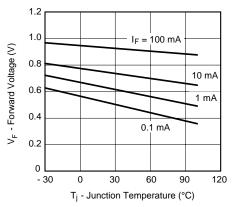


Figure 1. Forward Voltage vs. Junction Temperature

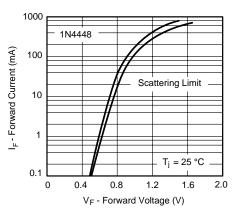


Figure 3. Forward Current vs. Forward Voltage

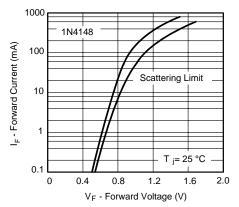


Figure 2. Forward Current vs. Forward Voltage

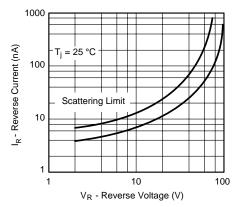


Figure 4. Reverse Current vs. Reverse Voltage

PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
DO-35	5000/AMMO	100000	41X28.5X38	14.57	13.07